Appl. No. 10/707,824
Amdt. dated January 23, 2006
Reply to Office action of October 24, 2005

No amendments have been made to the claims, and the claims are listed merely for reference:

<u>Listing of Claims:</u>

1.   (original) A method of defect review comprising following steps:

5   providing a wafer with a plurality of defects;

performing a defect inspection to detect the defects;

performing an automatic defect classification according to a database to separate the

defects into a plurality of defect types; and

performing a defect review;

10   wherein each defect type has different sampling ratios in the defect review according

to its influence degree of process yield.

2.   (original) The method of claim 1 wherein the database comprises information about

the plurality of defect types and defect information corresponding to each defect type.

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3.   (original) The method of claim 2 wherein the defect information comprises the

influence degree of the process yield of each defect type.

4.   (original) The method of claim 3 wherein the database separates the defect types

20   into killer defects and non-killer defects according to the influence degree of the process

yield.

5.   (original) The method of claim 4 wherein the sampling ratio of the killer defects in

the defect review is larger than that of the non-killer defects.

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6.   (original) The method of claim 3 wherein the database separates the defects into

pre-layer defects and adding defects, and further separates the adding defects into killer

defects and non-killer defects.

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7.   (original) The method of claim 6 wherein the defect review focuses on the adding defects.

5   8.   (original) The method of claim 1 wherein after finishing the defect inspection, a judgment of cluster defects is performed and a defect review with a high sampling ratio is performed on the cluster defects if the cluster defects exist.

9.   (original) The method of claim 1 wherein the database is updated according to the
10   result of the defect review after finishing the defect review.

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